

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (canceled)
2. (currently amended) The method of constructing a composite structure as defined in claim 13, further comprising the step of providing at least one capacitor within said dielectric material prior to the step of applying said dielectric material, said at least one capacitor being electrically connected between said electrical network and a conductive member.
3. (currently amended) The method of constructing a composite structure as defined in claim 13, further comprising the step of providing said electrical network with at least one conductive wire segment and electrically isolating said electrical network and said thermal network.
4. (canceled)
5. (currently amended) The method of constructing a composite structure as defined in claim 13, further comprising the step of selectively removing portions of a major surface of said electrical conductor to define at least one electrode area for mounting the semiconductor device thereon.
6. (currently amended) The method of constructing a composite structure as defined in claim 13, wherein said dielectric material comprises an alumina-based ceramic.

7. (currently amended) The method of constructing a composite structure as defined in claim 13, wherein said dielectric material comprises an organo-ceramic.
8. (canceled)
9. (currently amended) The method of constructing a composite structure as defined in claim 13, wherein said dielectric material comprises a silica-based ceramic.
10. (currently amended) The method of constructing a composite structure as defined in claim 13, further comprising the step of electrically connecting the at least one semiconductor device to said electrical conductor.
11. (currently amended) The method of constructing a composite structure as defined in claim 13, further comprising connecting the at least one semiconductor device to said electrical conductor and to said thermal conductor.
12. (currently amended) The method of constructing a composite structure as defined in claim 13, wherein the at least one electrical conductor includes a round conducting wire.
13. (previously presented) A method of constructing a composite structure for use with at least one semiconductor device, comprising the steps of:
 - providing at least one electrical conductor to form a portion of an electrical network;
 - providing at least one thermal conductor to form a portion of a thermal network;
 - and
 - applying a dielectric material to said electrical conductor by forming a direct covalent bond at a temperature less than 475 degrees C between said electrical conductor and said dielectric material by spray pyrolyzing a solution of metalorganic carboxylic acid salt precursors containing

polyvinyl butyral, said thermal network and said electrical network being encompassed by said dielectric material.

14. (previously presented) A method of constructing a composite structure for use with at least one semiconductor device, comprising the steps of:
 - providing at least one electrical conductor to form a portion of an electrical network;
 - providing at least one thermal conductor to form a portion of a thermal network;
 - affixing said thermal network to a mounting support; and
 - applying a dielectric material to said electrical conductor by forming a direct covalent bond at a temperature less than 475 degrees C between said electrical conductor and said dielectric material, said thermal network and said electrical network being encompassed by said dielectric material.